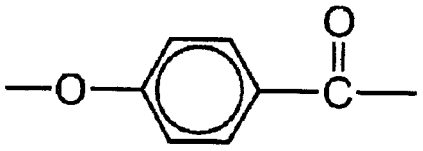
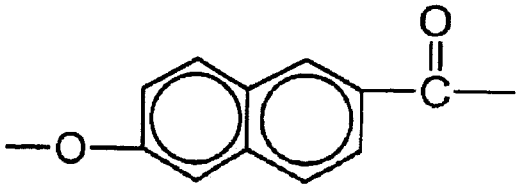
ABSTRACT

Provided are a composite resin composition that can provide an electronic component being excellent in heat resistance and having suppressed warping distortion and suppressed blister occurring, and an electronic component molded from the composite resin composition. The composite resin composition according to the present invention includes a liquid crystalline polymer (A), a fibrous filler (B), and a plate-shaped filler (C), in which the liquid crystalline polymer (A) is a wholly aromatic polyester amide that exhibits optical anisotropy when melted; the wholly aromatic polyester consisting of a predetermined amount of the following constituent units (I) to (VI) as essential constitutional components; and a weight average fiber length of the fibrous filler (B) is 250 μm or higher:

(I)



(II)



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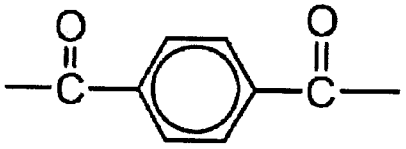

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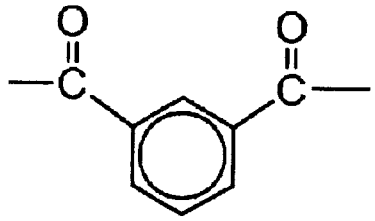

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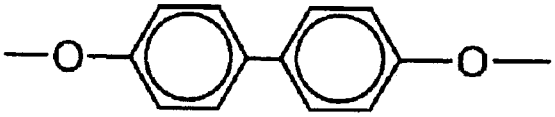
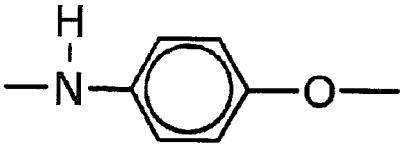


(VI)



[Fig. 1]